

# Semiconductor Integrated Circuit Device with EMI Prevention Structure

## Abstract of the Disclosure

A power lead and a ground lead are connected to corresponding pads of a die through an intra-package wiring substrate. A ground plane is formed in a mold under the intra-package wiring substrate extending along the bottom surface of the mold, and connected to the ground lead. A decoupling capacitor is connected to power wiring and the ground plane to prevent EMI caused by switching noise current generated by the power circuit of the die.

TECHNICAL FIELD